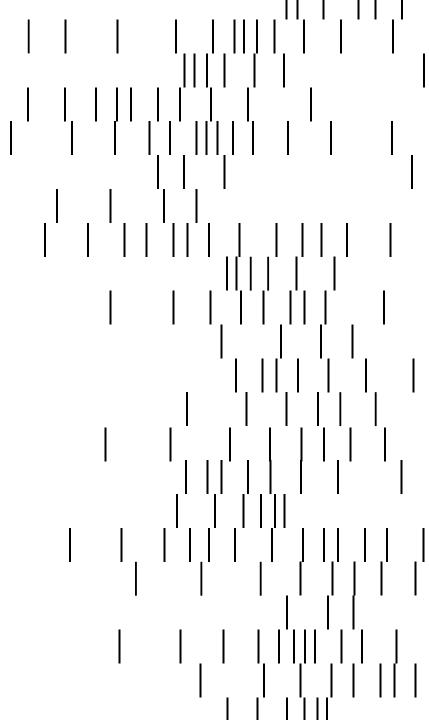


A Better Life on Earth

Time-of-Flight Mass Spectrometry for Highest Product Quality and a Clean and Safe Environment.



Agenda

| Key Benefits | 5 |
|----------------|----|
| Applications | 6 |
| Plasma Etching | 9 |
| Technology | 12 |
| Products | 15 |
| Product Usage | 19 |
| Performance | 22 |
| Competenices | 25 |

Key Benefits

Disruptive Solution



IN-LINE

Directly integrated with full remote control and supervision.



FULL QUANTITATIVE ANALYSIS & HEAVY MASSES

Full spectra up to 1200 u/e.



RESOLUTION & SENSITIVE

Unique insights into your production processes.

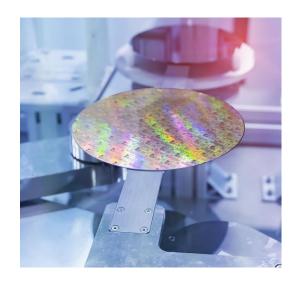


REAL-TIME

Full quantitative chemical analysis up to ten times per second.

Applications

Real-Time, In-Line and Full Quantitative Composition Monitoring





CVD, PVD, ALD, and Etching Process Control

> Yield increase



Laboratory

Full Quantitative Analysis, Speed, and Resolution

Increased sample throughput



Environmental

Full Quantitative Analysis, Speed, and Resolution

Seamless sample throughput



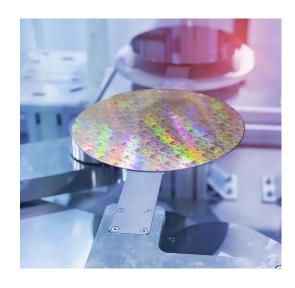
Academia

Research & Development with Full Quantitative Analysis

> Shortened development time

Applications

Yield increase in Semiconductor Industry



Wafer Manufacturing
CVD, PVD, ALD, and Etching
Process Control

Humidity Detection

Detection of humidity after maintaining the process chamber

> In-line, resolution

Contamination Detection

Detection and analysis of contamination events – at present and in the past

In-line, full quantitative analysis, heavy masses, resolution, real-time

Cleaning

Control the time needed for process chamber purging

> In-line, full quantitative analysis, heavy masses, resolution, real-time

Minimize dead time during maintenance

> increased yield

Detection of faults during each production step and preventing error propagation

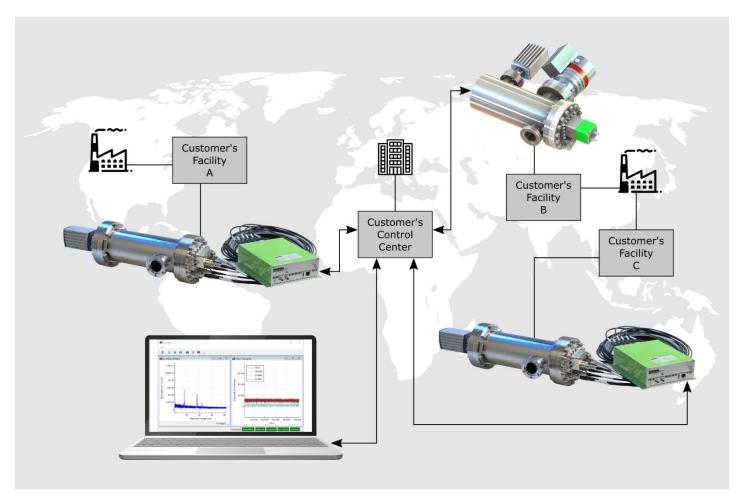
> increased yield

Minimize dead time during processing

> increased yield

Seamless Integration

Compact, In-Line, Online, 100% Remote Operation



Plasma etching of Silicon wafer

Plasma etching chamber

RF Plasma Etcher

- Chamber:
 - APPLIED MATERIALS MxP+ 200mm Etch Chamber
- Process Gas:
 - Cl2, NF3, H2, CF4, O2, Ar, N2
- Dry Pump:
 - Pumping Speed: 160 m3/h
- Turbo Pump:
 - Rated speed: 48000 RPM
 - Pumping speed for H2: 220 l/s
 - Pumping speed for N2: 300 l/s
 - Maximum Vacuum Pressure: 10⁻⁹ Torr
- RF Power Range : ~1200 W

IonTamer™

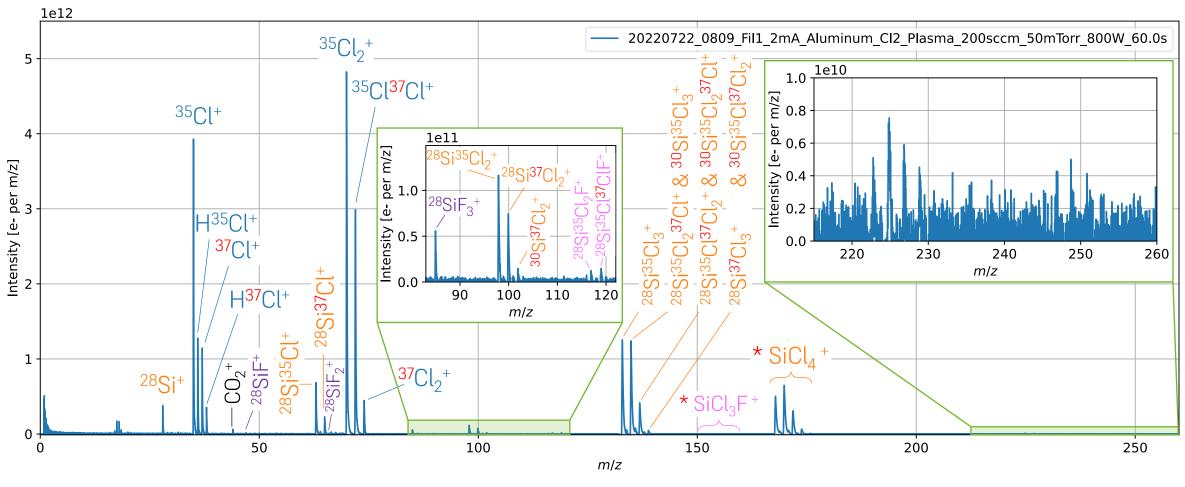
- TOFMS compact process analyzer
- Installed at turbo pump exhaust line



2022-09-05

Cl₂ plasma etching of Silicon wafer

Each measuring point: fully quantitative – high mass accuracy – heavy masses



Cl₂ plasma etching of Silicon wafer

Full quantitative analysis – high mass accuracy – heavy masses

Process description:

- Silicon dummy wafer
- Etching with chlorine plasma

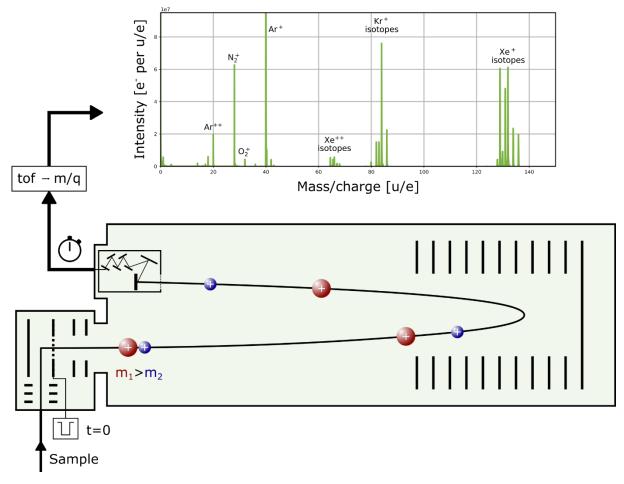
Analysis:

- Process gas (chlorine) is detected, including
 - Natural isotopes
 - Fragmentation pattern due to ionization
- Reaction products
 - Silicon tetrachloride (SiCl₄)
 - Group of peaks due to isotopologues
 - -Fragmentation pattern due to ionization: SiCl₃, SiCl₂, SiCl
 - Heavy reaction products at m/z > 200
 - Reaction products with silicon, chlorine, and fluorine
 - -Identified thanks to high resolution. However, fluorine was not used for the experiment
 - Cross contamination from previous experiments
 - Reaction products with water/humidity in vacuum chamber
 - Chlorine reacted with water residuals and formed hydrochloric acid (HCl)

2022-09-05

Technology

Time-of-Flight Mass Spectrometer for in-situ analysis



Key Performance Parameters

The TOF-RGA

| Mass range | 1 – 1200 u/e |
|---------------------|-----------------------------------|
| Mass accuracy | ±0.005 u/e |
| Mass resolution | 1200 m/Δm at Xe |
| Dynamic range | >10 ⁷ |
| Detection limit | <0.1 ppm |
| Speed | 10 full spectra per second |
| Detector | Dynode |
| Electron Ionization | Tungsten or yttria-coated iridium |





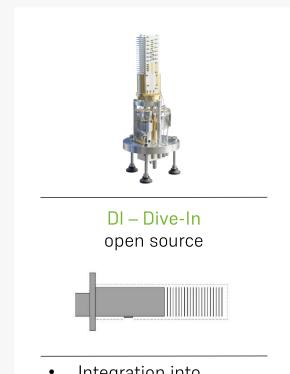
Technology Comparison Matrix

Process Mass Spectrometry

| | Quadrupole | | IonTamer™ Time-of-Flight (TOF) | | Laboratory Time-of-Flig | ht |
|-------------------------------------|---------------------------------|---|-----------------------------------|----------|---------------------------|----|
| Mass accuracy | ±0.5 u/e | × | ±0.005 u/e | | ±0.005 u/e or smaller | |
| Mass range | 1-100/1-200/1-300 u/e | | 1-1200 u/e | | 1-1000 u/e or more | |
| Acquisition | Individual masses in a sequence | × | All masses simultaneously | V | All masses simultaneously | |
| Full quantitative chemical analysis | No | × | Yes | ✓ | Yes | |
| Size | Compact (20 kg or less) | | Compact (14kg -25kg) | | Large (93kg and more) | × |
| Environment | Industrial | | Industrial | | Laboratory | × |
| Used Materials | Accepted by semi industry | | Accepted by semi industry | | Only for laboratory usage | × |

TOF Residual Gas Analyzer

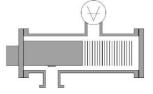
IonTamer™ Series



 Integration into existing equipment



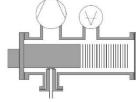
FA – Flanged open source



- Direct connection to high vacuum
- Standard CF40 flange



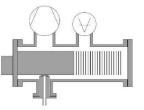
PS – Pumping System closed source



- Low vacuum operation sensitive
- Mobile version for research & development

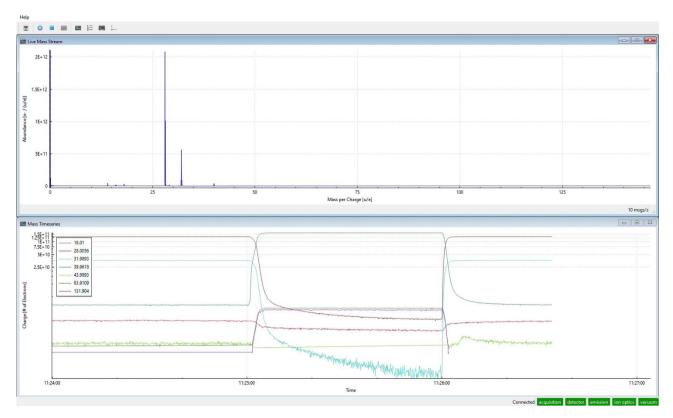


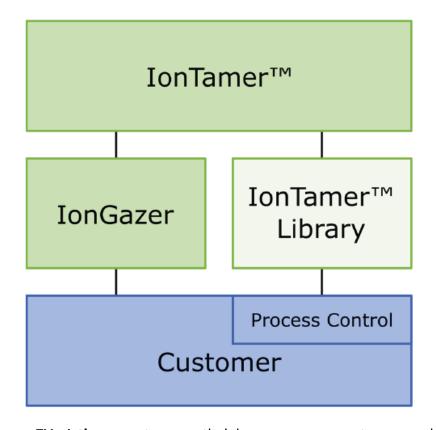
cPS – Compact System closed source



- Low vacuum operation
 sensitive
- Extra modular for compact integration

Software Products



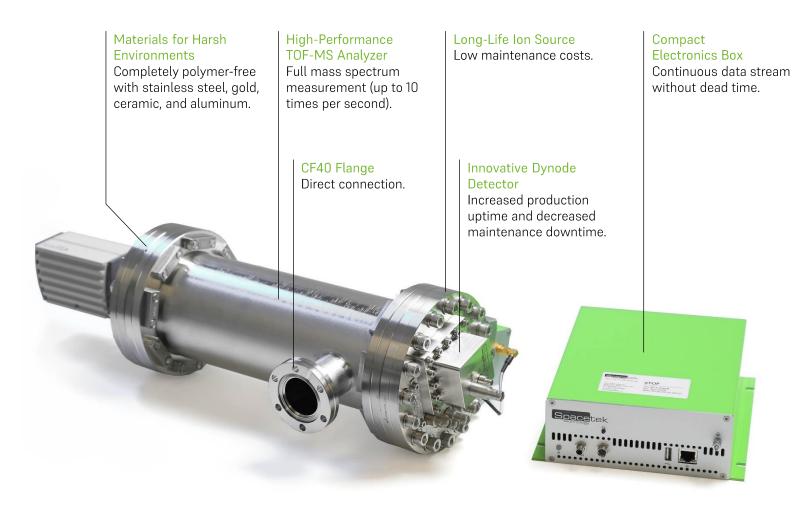


The lonGazer is an interactive desktop user interface software for central control of the IonTamer™, visualization of the measurement data in real time, recording of the data stream to storage, and real-time data analysis.

The **lonTamer™** Library is available as an option and provides data processing algorithms and usage examples to allow integration of the IonTamer™'s data stream into customer's applications and data pipelines.

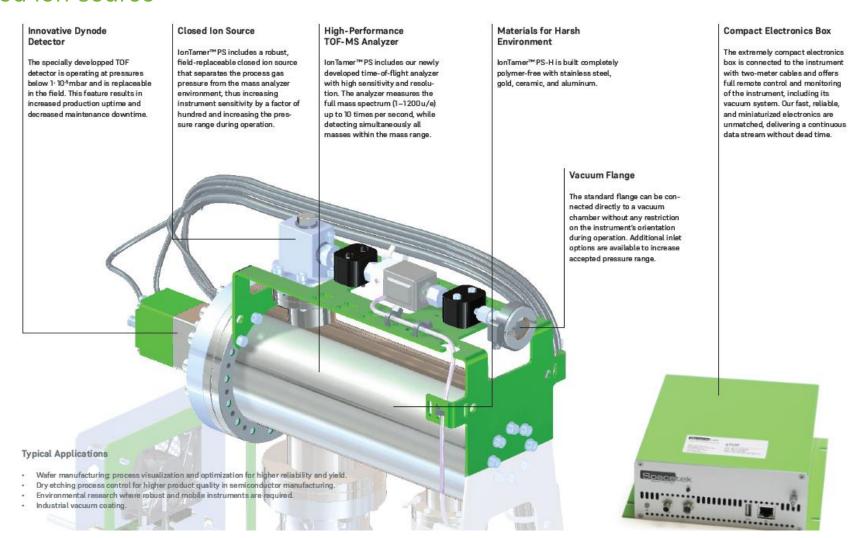
IonTamer[™] FA

TOF-RGA for high vacuum with open ion source



IonTamer™ PS

TOF-RGA with closed ion source



Periodical NEW Transistor Structures

Moore's law – the number of transistors in a dense integrated circuit doubles about every two years



Development of new processes of the next generation transistor structure:

Spacetek's *lonTamerTM PS* is the first mobile technology to completely visualize of seamless vacuum manufacturing processes for significantly shortened development times.



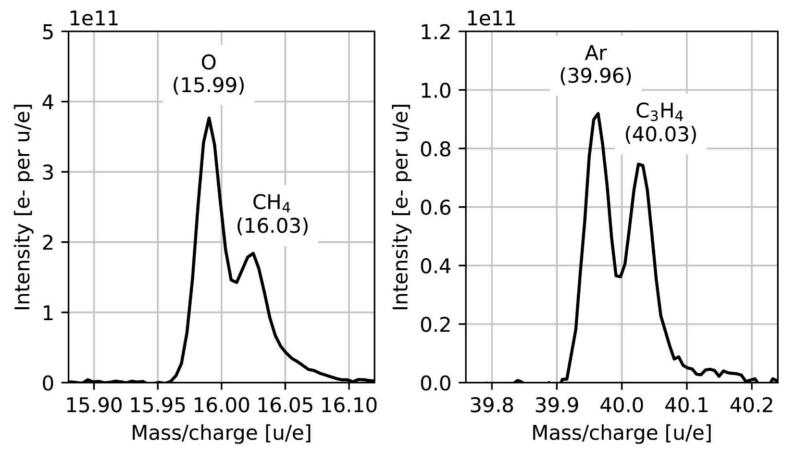
Establishing process control of the new transistor structure in new production lines:

Minimizing of dead time during production and maintenance including detection of faults during each production step with the capability to prevent the propagation of such errors. The wafer production yield can be increased up to several percentage with Spacetek's *lonTamer* TM CPS .



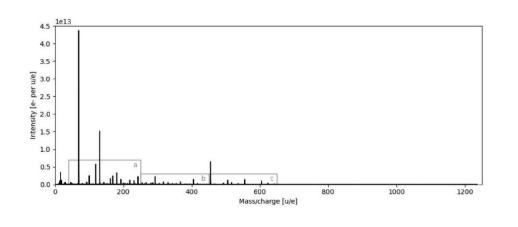
Resolution of Isobaric interferences

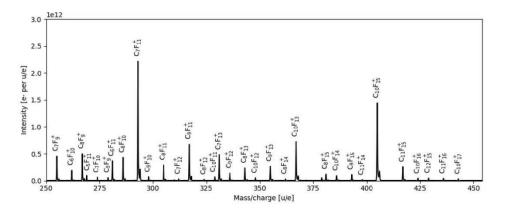
Separation of atomic oxygen and methane, or argon and C₃H₄

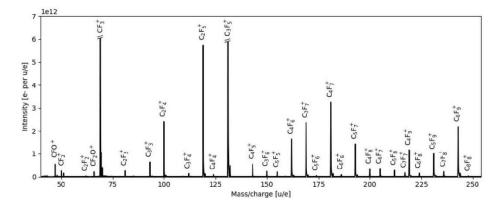


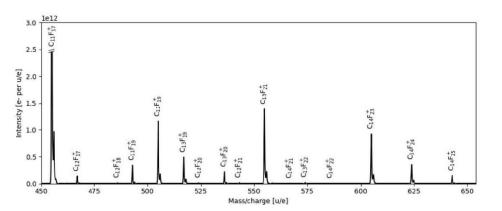
Analysis of heavy masses

Calibration substance FC5311 mass spectrum acquired with 70 eV & 180s integration



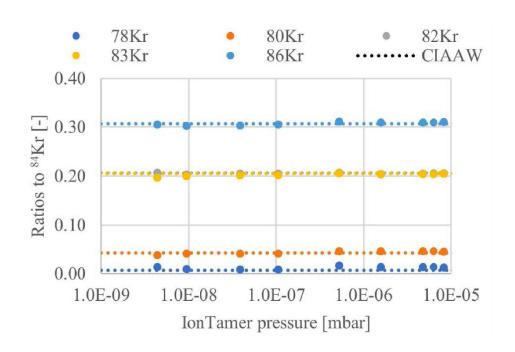


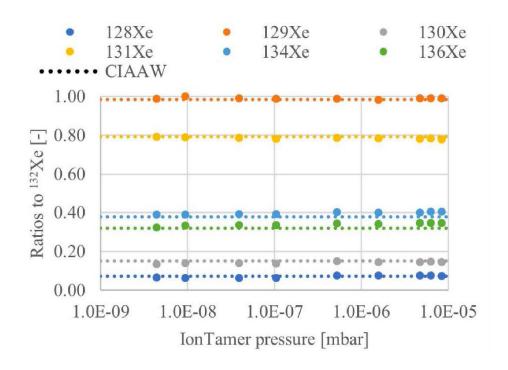




Excellent quantification – we count every ion!

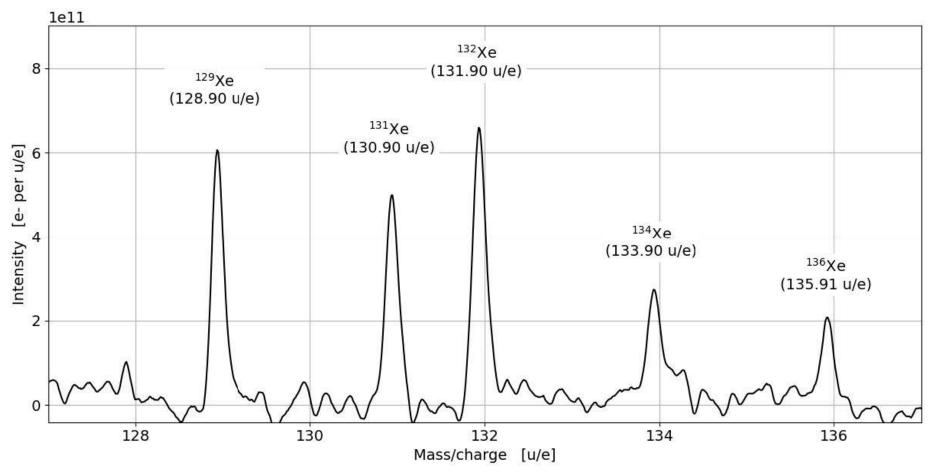
Analysis of Krypton and Xenon with high Accuracy, Repeatability & Reproducibility





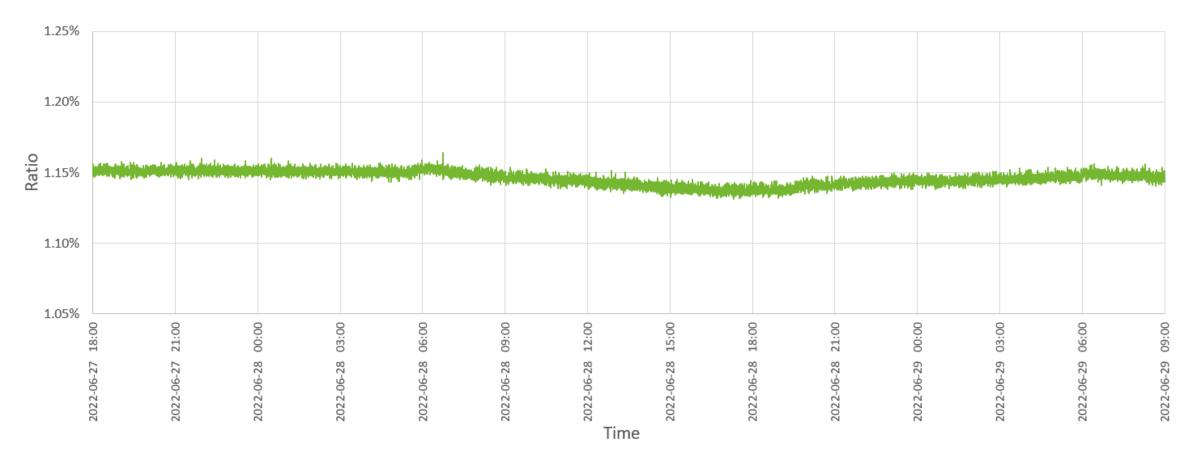
Measurement of Xenon in Air

Analysis down to 7.5 ppb



Long-term stability

Variation of the ⁴⁰Ar ratio over time



Note: the observed variations are due to a high temperature difference during the day-night cycle in summer.

Competencies

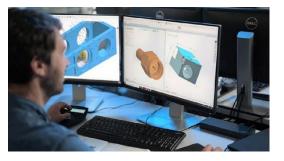
System integration, interface adaptation, production, calibration and analysis



Ion Optics



Electronics



Mechanics



Software

spacetek

Thank you!

Let us work together for a better life on Earth

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